



Part Number:		AS4C16M16D1-5BCN / AS4C16M16D1-5BIN								
Part Weight:		190mg								
No.	Part Name	Material Name	Component wt (mg)	Material Content (Element)	CAS Number	Element wt (%)	Element wt (mg)	wt % of Total unit wt	PPM	
1	Substrate	HL-832NX / AUS 308	64.485	Bismaleimide Triazine resin	105391-33-1	2.85%	1.838	0.97	28498.86	
				Epoxy resin -1	25722-66-1	2.85%	1.838	0.97	28498.86	
				Epoxy resin -2	9003-36-5	2.85%	1.838	0.97	28498.86	
				Inorganic Filler	21645-51-2	5.13%	3.309	1.74	51306.84	
				Continuous Filament Fiber Glass	65997-17-3	8.55%	5.513	2.90	85496.58	
				Talc containing no asbestiform fibers	14807-96-6	0.81%	0.519	0.27	8052.00	
				Morpholine derivative	Trade secret	0.81%	0.519	0.27	8052.00	
				Barium sulfate	7727-43-7	9.06%	5.841	3.07	90585.00	
				Silica, amorphous	7631-86-9	0.20%	0.130	0.07	2013.00	
				Dipropylene glycol monomethyl ether	34590-94-8	4.83%	3.115	1.64	48312.00	
				Epoxy resin A	Trade secret	2.62%	1.688	0.89	26169.00	
				Epoxy resin B	85954-11-6	1.81%	1.168	0.61	18117.00	
				Copper	7440-50-8	55.94%	36.073	18.99	559400.00	
				Nickel	7440-02-0	1.53%	0.987	0.52	15300.00	
Gold	7440-57-5	0.17%	0.110	0.06	1700.00					
2	Mold compound	G770SY	97.905	Epoxy resin A	Trade Secret	4.05%	3.964	2.09	40485.83	
				Epoxy resin B	Trade Secret	4.05%	3.964	2.09	40485.83	
				Phenol Resin A	Trade Secret	4.05%	3.964	2.09	40485.83	
				Phenol Resin B	Trade secret	4.05%	3.964	2.09	40485.83	
				Metal Hydroxide	Trade secret	2.02%	1.982	1.04	20242.91	
				Carbon black	1333-86-4	0.40%	0.396	0.21	4048.58	
				Silica fused	60676-86-0	68.83%	67.384	35.47	688259.11	
				Silica fused	7631-86-9	12.15%	11.891	6.26	121457.49	
				Silica, crystalline	14808-60-7	0.40%	0.396	0.21	4048.58	
3	Epoxy	2025D	0.433	Silica,amorphous,fued	60676-86-0	45.45%	0.197	0.10	454500.00	
				Bismaleimide monomer	Trade Secret	31.82%	0.138	0.07	318200.00	
				Acrylate monomer	Trade secret	9.09%	0.039	0.02	90900.00	
				Epoxy resin	Trade Secret	9.09%	0.039	0.02	90900.00	
				Acrylic resin	Trade secret	4.55%	0.020	0.01	45500.00	
4	Solder ball	Sn/Ag/Cu	21.174	Tin	7440-31-5	96.50%	20.433	10.75	965000.00	
				Silver	7440-22-4	3.00%	0.635	0.33	30000.00	
				Copper	7440-50-8	0.50%	0.106	0.06	5000.00	
5	Gold wire	Au	0.235	Gold	7440-57-5	99.99%	0.235	0.12	999900.00	
				Others	Trade Secret	0.01%	0.000	0.00	100.00	
6	Die	Chip	5.768	Silicon	7440-21-3	100.00%	5.768	3.04	1000000.00	
			190				600.00%	190.000	100.00	6000000